



QuickLogic Investor Presentation

December 2017

Brian Faith, CEO
Sue Cheung, Ph.D., CFO

NASDAQ: QUIK

Safe Harbor Statement

This press release contains forward-looking statements regarding our future business expectations, which are subject to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. These forward-looking statements are only predictions and may differ materially from actual results due to a variety of factors including: delays in the market acceptance of the Company's new products; the ability to convert design opportunities into customer revenue; our ability to replace revenue from end-of-life products; the level and timing of customer design activity; the market acceptance of our customers' products; the risk that new orders may not result in future revenue; our ability to introduce and produce new products based on advanced wafer technology on a timely basis; our ability to adequately market the low power, competitive pricing and short time-to-market of our new products; intense competition, including the introduction of new products by competitors; our ability to hire and retain qualified personnel; changes in product demand or supply; capacity constraints; and general economic conditions. These and other potential factors and uncertainties that could cause actual results to differ from the results predicted are described in more detail in the Company's public reports filed with the Securities and Exchange Commission (the "SEC"), including the risks discussed in the "Risk Factors" section in the Company's Annual Reports on Form 10-K, Quarterly Reports on Form 10-Q and in the Company's prior press releases, which are available on the Company's Investor Relations website at <http://ir.quicklogic.com/and> on the SEC website at www.sec.gov. QuickLogic expressly disclaims any obligation to update or revise any forward-looking statements found herein to reflect any changes in Company expectations or results or any change in events.

QuickLogic uses its website, the company blog QuickLogic HotSpot, corporate Twitter account, Facebook page, and LinkedIn page as channels of distribution of information about its products, its planned financial and other announcements, its attendance at upcoming investor and industry conferences, and other matters. Such information may be deemed material information, and QuickLogic may use these channels to comply with its disclosure obligations under Regulation FD.

Maximizing Battery Life for Immersive User Experiences in Smartphone, Wearable, Hearable & IoT devices

Always-on, Always-Listening

HQ in Silicon Valley | R&D: Sunnyvale, Bangalore | Field Sales and Support: Japan, South Korea, China, Taiwan and UK | Technical Staff – 68%

Maximizing Battery Life for Immersive User Experiences in Smartphone, Wearable, Hearable & IoT devices

Always-on, Always-Listening



Artificial intelligence



Reacts accurately to voice commands



Proactively interprets user context



EOS™ S3

Always-on / Always-listening
Ultra-low power
Product design flexibility

ArcticPro™

eFPGA IP
eFPGA compiler
eFPGA place and route tools
Foundry partners



Contextually aware services



Longer battery life



User flexibility

HQ in Silicon Valley | R&D: Sunnyvale, Bangalore | Field Sales and Support: Japan, South Korea, China, Taiwan and UK | Technical Staff – 68%

Investment Rationale

Addressing Critical Needs	<ul style="list-style-type: none">▪ Enabling significantly longer battery life, more immersive user experience & BOM integration▪ Essential for Smartphones, Wearables, Hearables and IoT
Tier 1 Customers & Ecosystem Partners	
Creating Competitive Advantages	<ul style="list-style-type: none">▪ 50+ patents in core IP▪ Delivers flexibility and reduced R&D costs for System on a Chip (SoC) vendors▪ Enabling new form factors, new use cases▪ Mobile-specific programmable logic enables hardware differentiation
Validating Technology	
Driving to Profitable Growth	<ul style="list-style-type: none">▪ Tier 1 Smartphone OEM Wearable now in the process of expanding its field testing to include several hundred users to prepare for the production launch▪ New design wins for Wearable, Hearable, and IoT markets▪ Entering new markets with eFPGA IP licensing opportunities

Product Lines

Sensor Processing

- Multi-core SoC for sensor processing, immersive user experience of sensor fusion and always-on deeply embedded voice recognition

Ultra-Low Power Programmable Logic (FPGAs)

- Available as discrete devices, integrated into our multi-core SoCs, or available for IP licensing

Display Bridges and Connectivity

- Solves interface mismatches between Application Processors and Displays
- MIPI DSI, RGB, and LVDS display support

Multiple Products & Markets

Sensor Processing

FOXCONN



runtastic



Telepathy



SK telecom



Top Tier Engagements



FPGA

KYOCERA



JRC



HUAWEI



SHARP



THINKWARE



Display Bridges

G'FIVE
WATER WORLD
HiFlyway



UNICAIR
Communication

FLY AUDIO

hp



SAMSUNG



SHARP



Sensor Processing



EOS™ S3

- Always-on / Always-listening
- Ultra-low power
- Product design flexibility

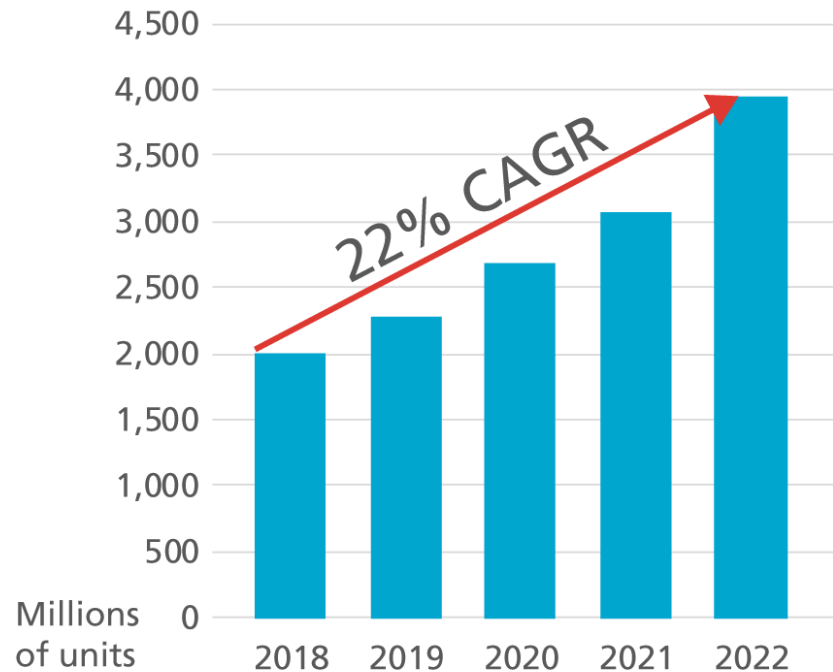
ArcticPro™

- eFPGA IP
- eFPGA compiler
- eFPGA place and route tools
- Foundry partners

Serving High Growth, High Volume Markets

1.5B Units in 2022

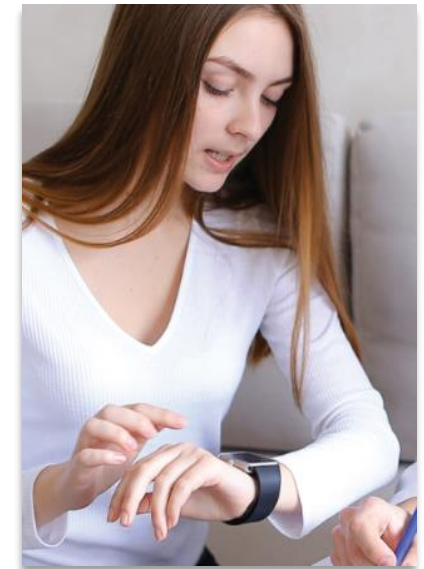
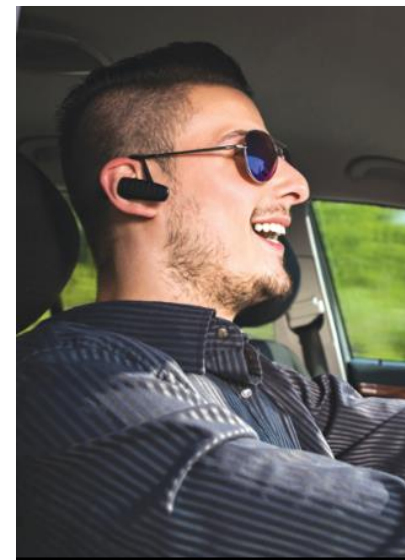
Discrete sensor hub market



Source: Daniel Associates, 2017

Market Drivers...

- More intelligence
- Contextually aware services
- Longer battery life
- **More computing at the edge**

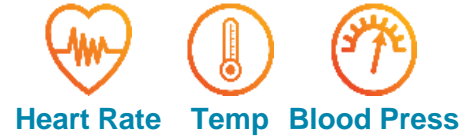


Immersive User Experience Requires More Sensors

Motion Sensors



Biological Sensors



Environmental Sensors



Gesture Sensors



Always-On / Always Listening Sensors Connect to the Cloud

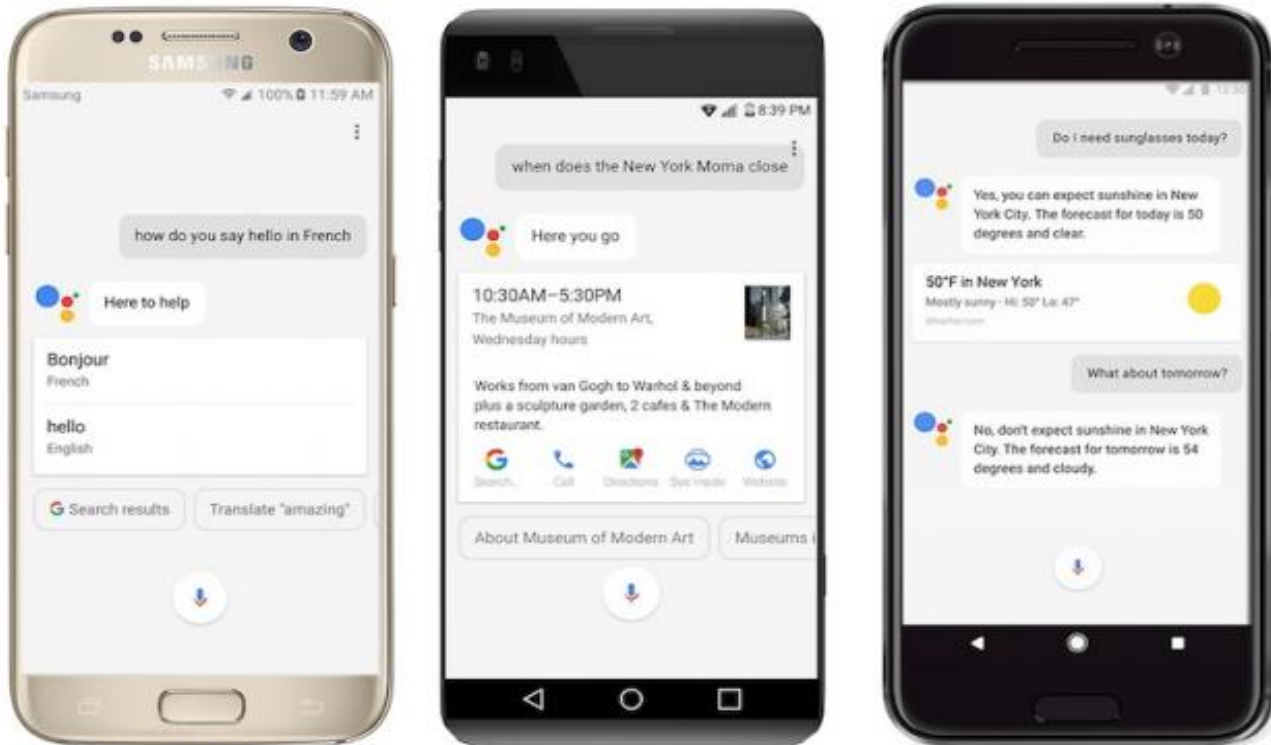
Driven by Voice-Enabled Experience



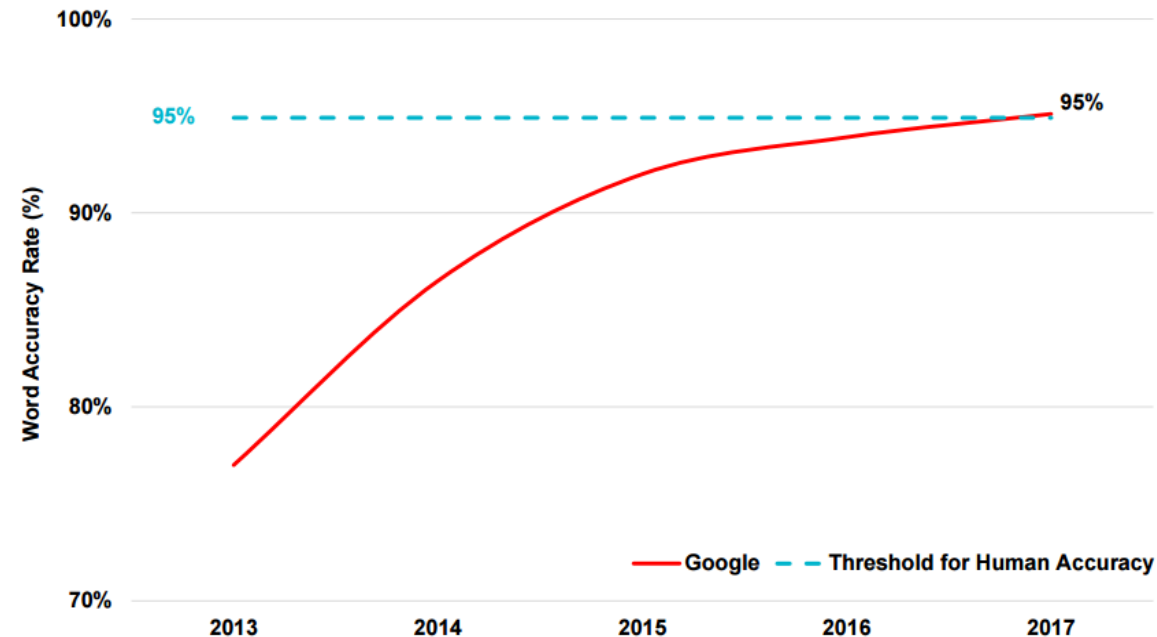
Voice Accuracy Reaching Human Levels

Voice Interfaces are Replacing Touch Interfaces

20% of Mobile Queries Made via Voice, 5/16



Google Machine Learning
Achieving Higher Word Accuracy, 2013-2017



Source: Mary Meeker / Kleiner Perkins
Annual Internet Trends Report, June 2017

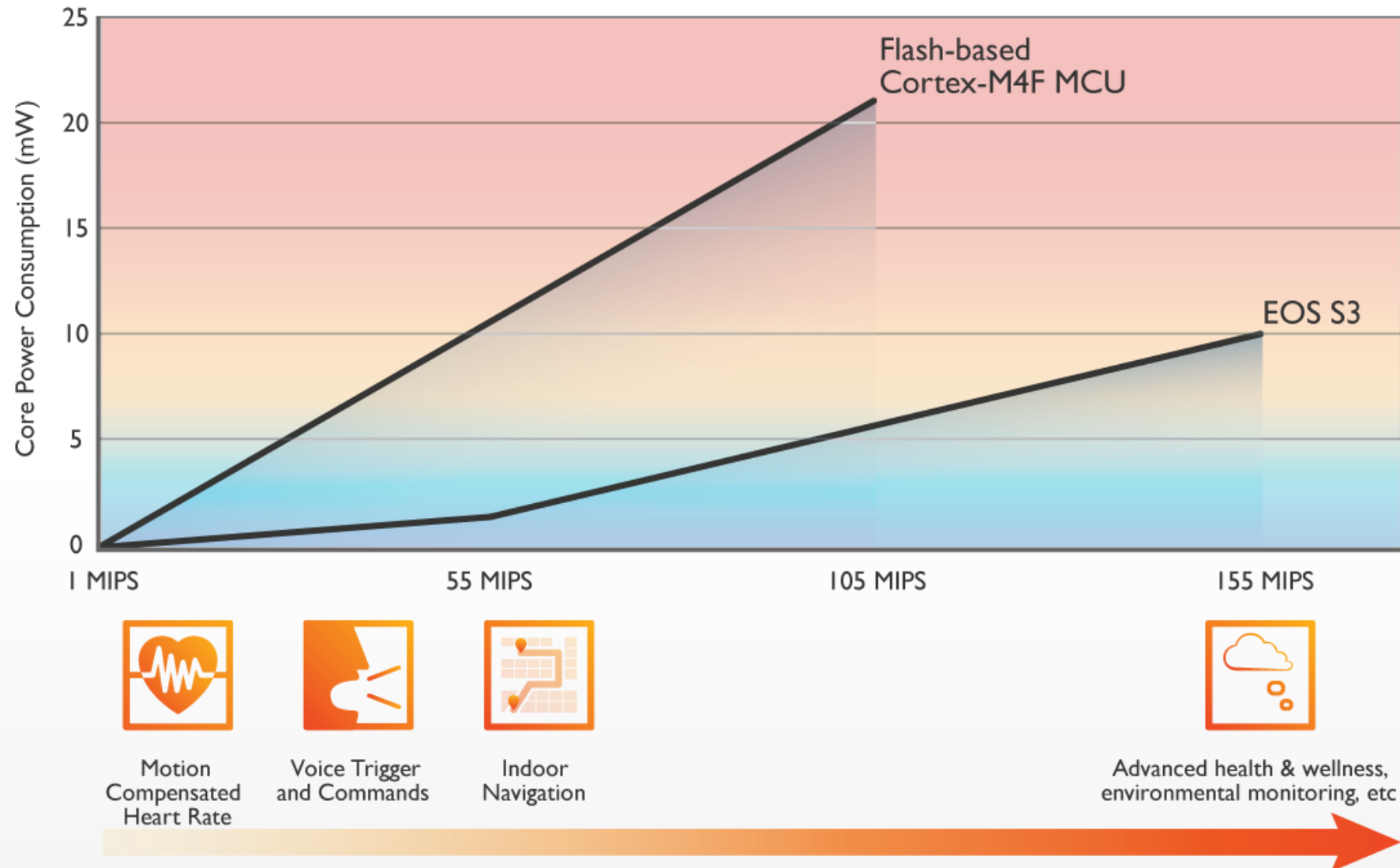
Voice-Enabled Artificial Intelligence

Focus of Both Large, and Emerging Technology Companies



CTO of a large hearable company called EOS S3 a
“masterpiece in system engineering”

The More Immersive the Experience, the Greater Our Advantage



Our EOS™ S3 is Lower Power than All Other Architectures



Discrete
Sensor Hub

AP-Integrated
MCU/DSP

Sensor with Integrated
MCU

2018 Market Share	683Mu, 34% of TAM	869Mu, 44% of TAM	440Mu, 22% of TAM
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QuickLogic is 1/2 the power of other discrete sensor hubs

Source: Daniel Associates, 2017



Ecosystem Partnerships

Optimizing Immersive User Experience



Leading supplier of deeply embedded voice recognition technology



Smarter Things

World leading vendor of Bluetooth® low energy Systems-on-Chip (SoCs)



Leading supplier of Android-compliant sensor fusion algorithms for Chinese OEMs



Rapidly growing leading enterprise provider of Artificial Intelligence (AI) speech technology

Sensor Processing Momentum

Emerging Markets & Opportunities



Wearables

Only 1/20th of the power budget of smartphones

- Expect app company product using EOS S3 will go into production in Q4 2017
- Janyun will use EOS S3 for voice-enabled GPS Smartwatch, targeted for Q4 production

Hearables

Only ½ of the power budget of Wearables

- Expect app company product using EOS S3 will go into production in Q4 2017
- Qiwo Smartlink will use EOS S3 for Bluetooth® headset, targeted for Q4 production
- Expect several designs win enabled by QuickLogic EOS S3 at CES 2018
- Engaged with one of China's largest ODMs for a new hearable design

Dual Wearables & Hearables Product Customer – Tier One Smartphone Wearable now in the process of expanding its field testing to include several hundred users. Q2 started working on 2 new high-volume consumer wearable and hearable opportunities targeted for mass production during mid-2018.

Embedded FPGA (eFPGA) IP Licensing



EOS™ S3

Always-on / Always-listening

Ultra-low power

Product design flexibility

ArcticPro™

eFPGA IP

eFPGA compiler

eFPGA place and route tools

Foundry partners

Entering New Markets

eFPGA IP Licensing Positioning



- Targets significant financial potential
 - \$10M+ potential annual licensing revenue with upside on royalty revenue in 2+ years
- Creates new, very high gross margin manufacturing licenses revenue streams
- Delivers flexibility and reduced R&D costs for SoC vendors

The embedded semiconductor intellectual property (IP) market is expected to grow from \$3.09B to over \$7B by 2022, according to Markets&Markets.

eFPGA Benefits

Adding Post-Fabrication Flexibility to SoCs

Adds Flexibility – Enables complex functionality

Ultra-Low Power Consumption – Power optimized

Increased Performance – Eliminates chip-to-chip delays

Higher Revenues – Enables multiple product variants

Greater Profits – Closer match to market needs

Lower R&D Costs – Reduces development time & cost

Faster Time to Market – Supports post-fabrication changes

SEMICONDUCTOR ENGINEERING

Home > System-Level Design > Embedded FPGAs Come Of Age

SYSTEM-LEVEL DESIGN

Embedded FPGAs Come Of Age

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These devices are gaining in popularity for more critical functions as chip and system designs become more heterogeneous.

FEBRUARY 27TH, 2017 - BY: ANN STEFFORA MUTSCHLER



FPGAs increasingly are being viewed as a critical component in heterogeneous designs, ratcheting up their stature and the amount of attention being given to programmable devices.

Once relegated to test chips that ultimately would be replaced by lower-power and higher-performance ASICs if volumes were sufficient, FPGAs have come a long way. Over the last 20 years programmable devices have moved steadily up the food chain from glue logic to co-processors, and they have been utilized in a variety of high-performance, mission-critical applications from data centers to supercomputers.

Secured Two Top-tier eFPGA Foundries

- ArcticPro™, **first** eFPGA announced for **new** GLOBALFOUNDRIES' 22FDX® (FDSOI) process
- Supports 65nm and 40nm leveraging existing technology and foundry relationship with GLOBALFOUNDRIES
- Gained early access to GLOBALFOUNDRIES' 22nm FD-SOI Process by joining its FDXcelerator™ Partner Program
- Signed a semiconductor foundry manufacturing license agreement with SMIC for its 40nm process node
- Accelerates QuickLogic's access to leading edge process technology for our own silicon development



eFPGA Market Momentum

Partnered with AcconSys to expand ArcticPro eFPGA penetration in China.

Qualified ArcticPro™ eFPGA at SMIC to become the first eFPGA IP available on its low power 40nm LL process.

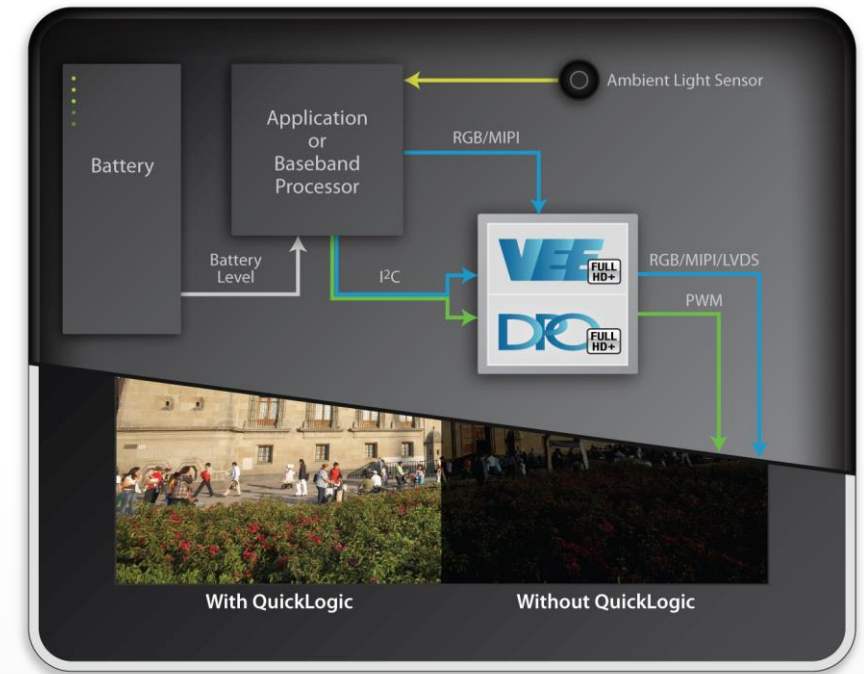
Established eFPGA IP Support Center in Taiwan to provide fast, local support for licensees, foundries and ecosystem partners

Appointed Bernie Rosenthal, co-founder of Tensilica, Inc. and a well-known tech entrepreneur, to QuickLogic's advisory board

Increased number of significant ArcticPro eFPGA engagements

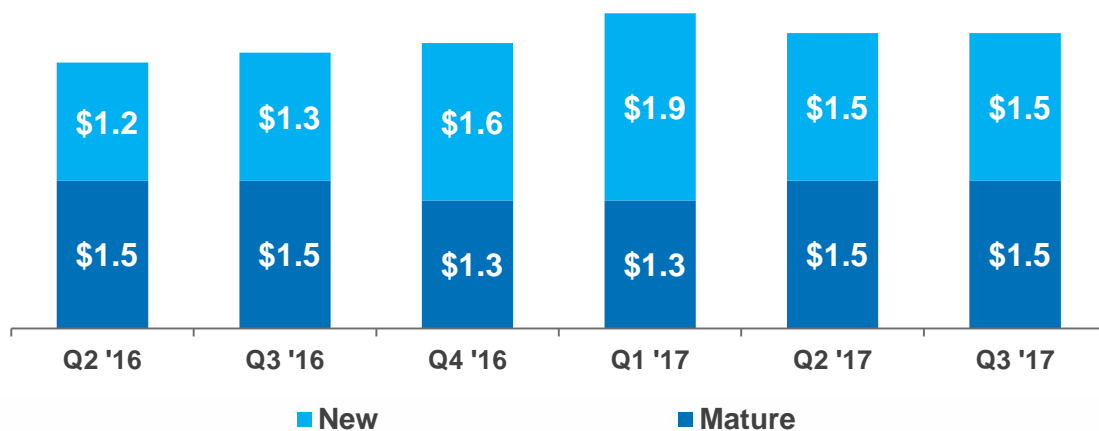
Display Bridge & Connectivity Products – Maintaining Momentum

- Continue to ship into consumer tablet market
- Working with new IoT module using a QuickLogic connectivity solution – expect production 1H 2018
- Expect to continue display bridge revenue well into 2018 and beyond with large OEMs

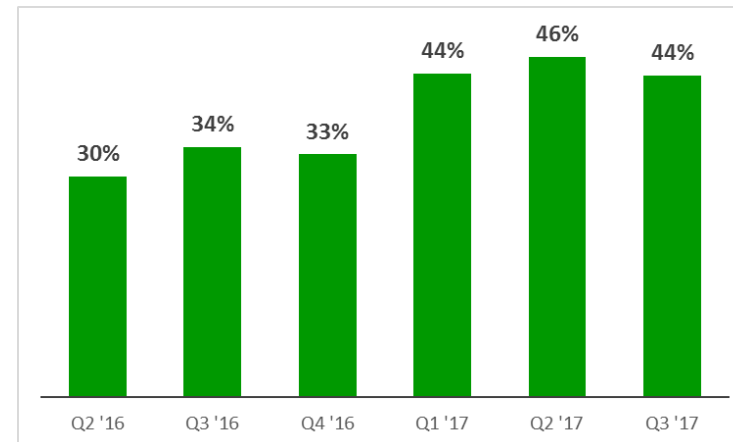


Historical Quarterly Financial Highlights

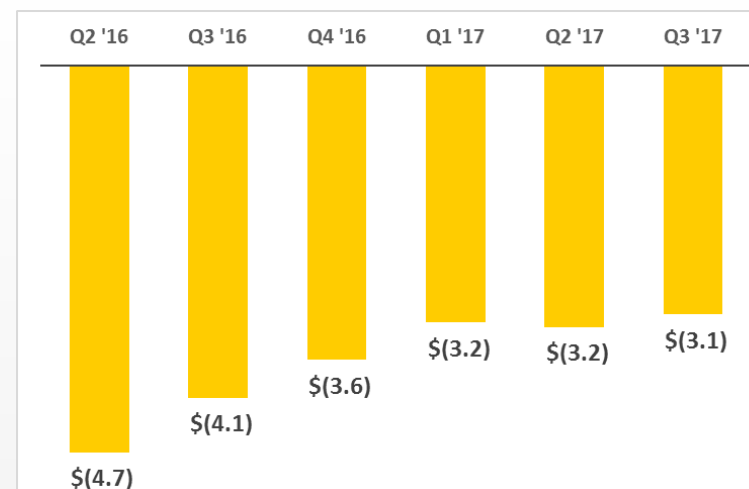
Revenue
(\$ in Ms)



Non-GAAP Gross Margin



Non-GAAP Net Loss*
(\$ in Ms)



Balance Sheet Data (Millions)	10/1/2017
Total Cash	\$19.0
Bank Debt - 4.00% Int.	\$6.0

Q4 2017 Financial Forecast

Non-GAAP	Q4'16	Q1'17	Q2'17	Q3'17	Q4'17
<i>(\$ in millions, except noted)</i>	Actual	Actual	Actual	Actual	Guidance
New Product Revenue	\$ 1.6	\$ 1.9	\$ 1.5	\$ 1.5	\$ 1.2
Mature Product Revenue	\$ 1.3	\$ 1.3	\$ 1.5	\$ 1.5	\$ 1.8
Total Revenue	\$ 2.9	\$ 3.2	\$ 3.0	\$ 3.0	\$ 3.0 +/- 10%
Non-GAAP Gross Margin	33%	44%	46%	44%	48% +/- 3%
R&D	\$ 2.3	\$ 2.3	\$ 2.2	\$ 2.2	\$ 2.3
SG&A	\$ 2.3	\$ 2.3	\$ 2.4	\$ 2.1	\$ 2.3
Total Expense	\$ 4.6	\$ 4.6	\$ 4.6	\$ 4.3	\$ 4.6 +/- \$300k
Other Income/expense/taxes	\$(106)k	\$(97)k	\$(53)k	\$(95)k	~ \$(60)k
Net Loss	\$ (3.7)	\$ (3.2)	\$ (3.2)	\$ (3.1)	\$ ~ (3.3)
Net Loss Per Share	\$ 0.05	\$ 0.05	\$ 0.04	\$0.04	~\$0.04

- Q4 2017 Cash usage expected to be between \$2.8M and \$3.2M, primarily driven by working capital needs and capital expenditure associated with our eFPGA and SoC development effort.**

Actual results may vary significantly due to things that are beyond the company's control, such as schedule variations from customers, schedule changes and projected production start dates could push or pull shipments. Forecast as of Nov. 8, 2017, Q3 2017 results conference call.

Target Operating Model

Targets	Mid Term (2 year)	Long Term (>2 year)
Revenue Growth	>50%	>50%
Non-GAAP Gross Margin	45 - 50%	>50%
Non-GAAP Operating Margin	0 - 10 %	10 - 15%+

Non-GAAP break-even revenue rate to between \$8.0M and \$10.0M/qtr. with a 45% - 50% gross margin

Actual results may vary significantly due to things that are beyond the company's control, such as schedule variations from customers, schedule changes and projected production start dates could push or pull shipments. Forecast as of Nov. 8, 2017, Q3 2017 results conference call.

QuickLogic Leadership

Executives

Brian Faith

Chief Executive Officer, Director

- Joined in 1996
- CEO in 2016
- VP of Worldwide Marketing/ VP of Worldwide Sales & Marketing 2008-2016
- Rising managerial & executive positions, including engineering, product line management, marketing and sales

Sue Cheung, Ph.D.

Chief Financial Officer

- Joined in 2007
- CFO in 2017, VP of Finance in 2016
- Principal Accounting Officer, Corp. Controller & Asst. Controller 2007-2016
- Sr. Accounting management positions at Dell SonicWALL, VeriFone and other publicly traded and privately held companies
- CPA and PH.D. in Business Administration

Timothy Saxe, Ph.D.

Chief Technology Officer & SVP Engineering

- Joined in 2001
- CTO in 2008, SVP of Eng. in 2016
- Rising executive positions including VP of Eng. and VP of Software Eng.
- VP of FLASH Engineering at Actel Corp. and founder/CEO of semiconductor mfg. division at GateField Corp. (Zycad)
- Doctorate in Electrical Engineering

Rajiv Jain

VP Worldwide Operations

- Joined in 1992
- VP Worldwide Ops in 2014
- Sr. Dir. of Operations & Development Eng., Sr. Dir. of System Solutions & Process Technology, Dir. of Process Technology, and Sr. Process Technologist 1992-2014
- Sr. Engineering positions at National Semiconductor and Monolithic Memories

Board of Directors

E. Thomas Hart

Chairman

- QuickLogic CEO 1994-2009
- VP & GM of Advanced Networking Division at National Semiconductor Corp.
- Senior Manager, Motorola, Inc.

Michael R. Farese

Director

- 35 years in executive roles in telecomm & semiconductor industry including Antenna29; Entropic Comm. Inc.; BitWave Semicon, Palm; WJ Comm; Tropian Inc.; Motorola Corp.; Ericsson Inc.; Nokia Corp.; ITT Corp.; AT&T Corp.; and Bell Labs

Arturo Krueger

Director

- Over 40 years leadership in systems architecture, semiconductor design & development, operations and marketing
- Executive roles at Motorola, Inc. semiconductor products; Director, Marvell Technology Group Ltd

Andrew J. Pease

Director

- QuickLogic CEO/President 2009-2016, VP Worldwide Sales 2006-2009
- Executive roles at Broadcom Corp.; Synticity, Inc.
- Various sales positions at Advanced Micro Devices; Integrated Systems Inc.; and Vantis Corp.

Daniel A. Rabinovitsj

Director

- COO, Ruckus Wireless, Inc.
- Executive roles at Qualcomm Atheros, Inc.; Atheros Communications; NXP Semiconductors; ST Ericsson; and Silicon Labs

Christine Russell

Director

- CFO, UniPixel, Inc., Vendavo, Inc.,
- CFO positions at Evans Analytical Group; Virage Logic Corp.; OuterBay; Ceva, Inc.; and Persistence Software, Inc.

Gary H. Tauss

Director

- Exec. Director & CEO, BizTech
- Executive roles at Mobidia Technology, Inc.; InfiniRoute Networks, Inc.; LongBoard, Inc.; and TollBridge Technologies

Investment Rationale

<p>Addressing Critical Needs</p>	<ul style="list-style-type: none"> Enabling significantly longer battery life, more immersive user experience & BOM integration Essential for Smartphones, Wearables, Hearables and IoT
<p>Tier 1 Customers & Ecosystem Partners</p>	
<p>Creating Competitive Advantages</p>	<ul style="list-style-type: none"> 50+ patents in core IP Delivers flexibility and reduced R&D costs for System on a Chip (SoC) vendors Enabling new form factors, new use cases Mobile-specific programmable logic enables hardware differentiation
<p>Validating Technology</p>	
<p>Driving to Profitable Growth</p>	<ul style="list-style-type: none"> Working with Tier 1 Smartphone OEM Wearable now in the process of expanding its field testing to include several hundred users to prepare for the production launch Entering new markets with eFPGA IP licensing opportunities Executing new initiatives for Wearable, Hearable, and IoT markets



Appendix

Non-GAAP Measures

QuickLogic reports financial information in accordance with GAAP, but believes that non-GAAP financial measures are helpful in evaluating its operating results and comparing its performance to comparable companies. Accordingly, the Company excludes charges related to stock-based compensation, restructuring, the effect of the write-off of long-lived assets and the tax effect on other comprehensive income in calculating non-GAAP (i) income (loss) from operations, (ii) net income (loss), (iii) net income (loss) per share, and (iv) gross margin percentage. The Company provides this non-GAAP information to enable investors to evaluate its operating results in a manner similar to how the Company analyzes its operating results and to provide consistency and comparability with similar companies in the Company's industry. Management uses the non-GAAP measures, which exclude gains, losses and other charges that are considered by management to be outside of the Company's core operating results, internally to evaluate its operating performance against results in prior periods and its operating plans and forecasts. In addition, the non-GAAP measures are used to plan for the Company's future periods, and serve as a basis for the allocation of the Company's resources, management of operations and the measurement of profit-dependent cash and equity compensation paid to employees and executive officers. Investors should note, however, that the non-GAAP financial measures used by QuickLogic may not be the same non-GAAP financial measures, and may not be calculated in the same manner, as that of other companies. QuickLogic does not itself, nor does it suggest that investors should, consider such non-GAAP financial measures alone or as a substitute for financial information prepared in accordance with GAAP. A reconciliation of GAAP financial measures to non-GAAP financial measures is included in the financial statements portion of this press release. Investors are encouraged to review the related GAAP financial measures and the reconciliation of non-GAAP financial measures with their most directly comparable GAAP financial measures.

P&L – Non-GAAP

Non-GAAP Results Millions (except for EPS)	Q3'16 Actual	Q4'16 Actual	FY 2016 Actual	Q1'17 Actual	Q2'17 Actual	Q3'17 Actual
New Product Revenue	\$1.3	\$1.6	\$5.6	\$1.9	\$1.5	\$1.5
Mature Revenue	\$1.5	\$1.4	\$5.8	\$1.3	\$1.5	\$1.5
Total Revenue	\$2.8	\$3.0	\$11.4	\$3.2	\$3.0	\$3.0
Gross Margin %	34%	33%	35%	44%	46%	44%
Research & Development	\$2.6	\$2.3	\$11.3	\$2.3	\$2.2	\$2.2
SG&A	\$2.4	\$2.3	\$9.5	\$2.3	\$2.4	\$2.1
Total Operating Expense	\$5.0	\$4.6	\$20.8	\$4.6	\$4.6	\$4.3
Operating Income (Loss)	(\$4.1)	(\$3.6)	(\$16.9)	(\$3.2)	(\$3.2)	(\$3.1)
Net Income (Loss)	(\$4.1)	(\$3.7)	(\$17.2)	(\$3.3)	(\$3.3)	(\$3.1)
EPS	(\$0.06)	(\$0.05)	(\$0.26)	(\$0.05)	(\$0.04)	(\$0.04)

GAAP to Non-GAAP Reconciliation

	Q3'16	Q4'16	FY 2016	Q1'17	Q2'17	Q3'17
(In \$ '000)	Actual	Actual	Actual	Actual	Actual	Actual
Non-GAAP Operating Loss	\$ (4,072)	\$ (3,610)	\$ (16,851)	\$ (3,150)	\$ (3,206)	\$ (3,050)
Stock-based Compensation	(457)	(125)	(1,583)	(318)	(347)	(395)
Restructuring Costs	-	-	-	-	-	-
FA impairment and/or write-off	(39)	(17)	(368)	-	-	(10)
GAAP Operating Loss	\$ (4,568)	\$ (3,752)	\$ (18,802)	\$ (3,468)	\$ (3,553)	\$ (3,455)

Non-GAAP Net Loss	\$ (4,127)	\$ (3,716)	\$ (17,197)	\$ (3,247)	\$ (3,260)	\$ (3,145)
Adjustments:						
Stock-based Compensation	(457)	(125)	(1,583)	(318)	(347)	(395)
FA impairment and/or write-off	(39)	(17)	(368)	-	-	(10)
GAAP Net Loss	\$ (4,623)	\$ (3,858)	\$ (19,148)	\$ (3,565)	\$ (3,607)	\$ (3,550)

Qiwo Smartlink Technology Chooses EOS S3 Multi-Core SoC for Voice-Enabled Bluetooth Headset Designs



EOS S3 & **sensory**
Voice Technology

Enabled by **AISPEECH**



“The **QuickLogic EOS S3 SoC** provided us the **lowest possible power consumption** for new voice enabled headsets,” said Fengko Gao, CEO of Qiwo. “With its multi-core design, **integrated voice technology** and inherent **flexibility to address multiple use cases**, we look forward to incorporating the EOS S3 solution in future wearable and IoT designs. We believe this strategy will help us accelerate new product development, address multiple use cases from a single platform and leverage the broad market penetration that Qihoo 360 has established in China.”

Janyun Chooses EOS S3 Sensor Processing Platform for Voice-Enabled GPS Smartwatch

- New design complements Janyun's successful line of wearable IoT products & cloud applications
- EOS S3 platform provides host processor, sensor processor, voice interface, GPS interface and display driver in the new design



“The QuickLogic EOS S3 SoC is an ***ideal solution for our wearable and IoT ODM designs***,” said Saicheng Tang, CEO of Janyun. “The EOS S3 platform provides us with a single chip, multi-core solution that optimizes our designs for cost, ultra-low power consumption, and design flexibility that enables us to support multiple end customer use cases with a single platform. We view these capabilities as ***essential to our success in the development of our ODM business model***.”